

DESCRIPTION

The MXN3342 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. It can be used in a wide variety of applications.

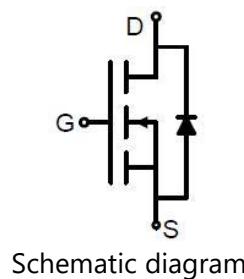
GENERAL FEATURES

- $V_{DS}=30V$, $I_D=35A$
- $R_{DS(ON)}(\text{Typ.})=10\text{m}\Omega$ @ $V_{GS}=4.5V$
- $R_{DS(ON)}(\text{Typ.})=6.5\text{m}\Omega$ @ $V_{GS}=10V$
- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

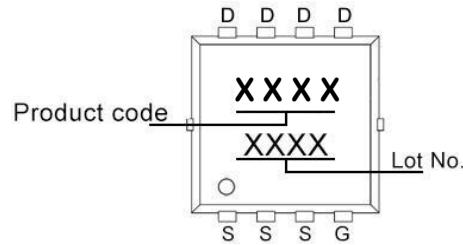
APPLICATION

- PWM applications
- Load switch
- Power management
- Battery

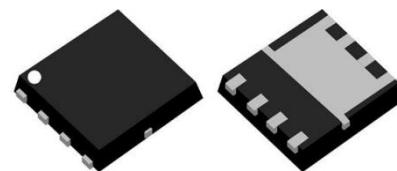
PINOUT



Schematic diagram



Marking and pin Assignment



DFN3X3-8L top view

ORDERING INFORMATION

Part Number	Storage Temperature	Package	Devices Per Reel
MXN3342	-55°C to 150°C	DFN3X3-8L	5000

ABSOLUTE MAXIMUM RATINGS ($T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	35	A
Drain Current-Continuous($T_C=100^\circ C$)	I_D	25	A
Pulsed Drain Current ^(Note1)	I_{DM}	100	A
Maximum Power Dissipation	P_D	25	W
Avalanche Current	I_{AS}	37	A
Avalanche Energy ($L=0.1\text{mH}$)	E_{AS}	68	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

THERMAL RESISTANCE

Thermal Resistance, Junction-to-Case ^(Note2)	$R_{\theta JC}$	5	°C/W
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Note 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Note 2. Surface Mounted on FR4 Board, $t \leq 10$ sec.


ELECTRICAL CHARACTERISTICS($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
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Off Characteristics

Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	30	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA

On Characteristics^(Note 3)

Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1	1.6	2.2	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=16\text{A}$	-	10	13	$\text{m}\Omega$
		$V_{\text{GS}}=10\text{V}, I_{\text{D}}=20\text{A}$	-	6.2	7.5	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=10\text{A}$	-	32	-	S

Dynamic Characteristics^(Note 4)

Input Capacitance	C_{iss}	$V_{\text{DS}}=15\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	1300	-	pF
Output Capacitance	C_{oss}		-	175	-	pF
Reverse Transfer Capacitance ^(Note 4)	C_{rss}		-	121	-	pF

Switching Characteristics

Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=15\text{V}, R_{\text{L}}=1\Omega, V_{\text{GS}}=10\text{V}, R_{\text{G}}=3\Omega$	-	4.2	-	nS
Turn-on Rise Time	t_{r}		-	8.2	-	nS
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	31	-	nS
Turn-Off Fall Time	t_{f}		-	4	-	nS
Total Gate Charge	Q_{g}	$V_{\text{DS}}=15\text{V}, I_{\text{D}}=10\text{A}, V_{\text{GS}}=10\text{V}$	-	28	-	nC
Gate-Source Charge	Q_{gs}		-	3.5	-	nC
Gate-Drain Charge	Q_{gd}		-	7	-	nC

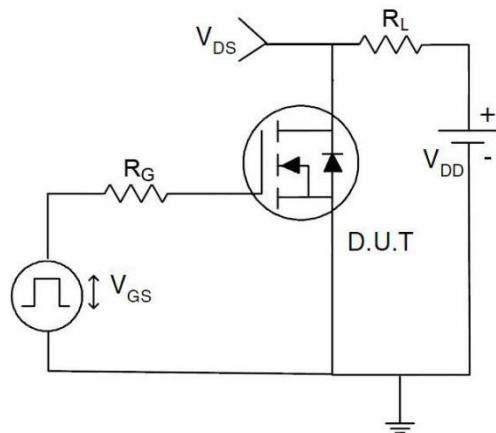
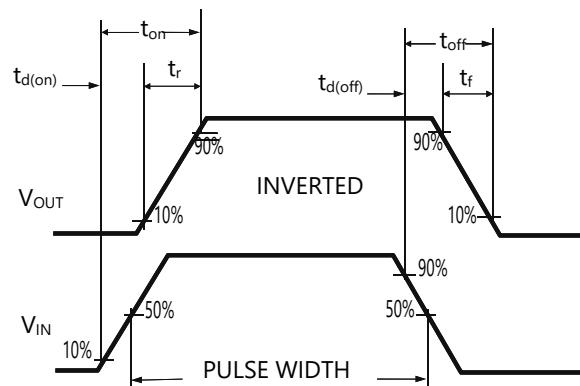
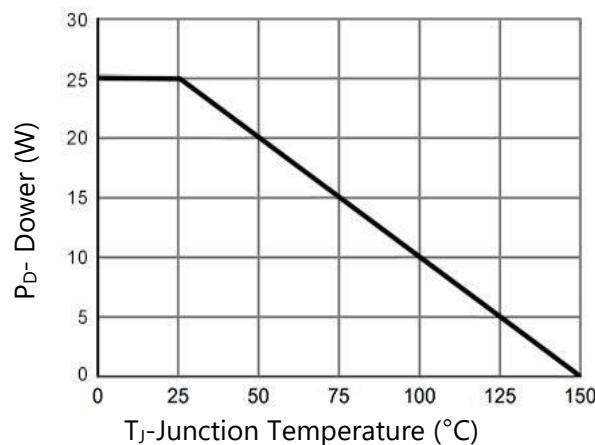
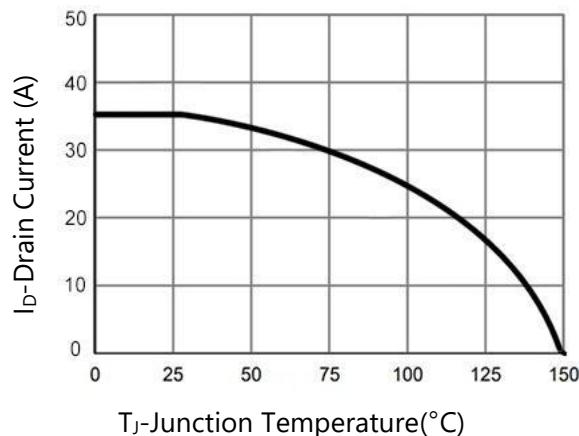
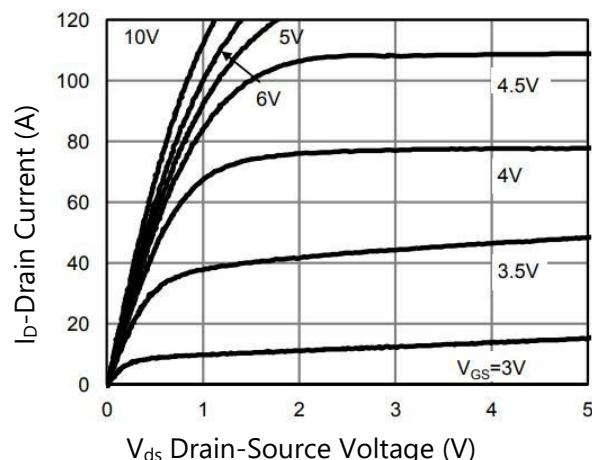
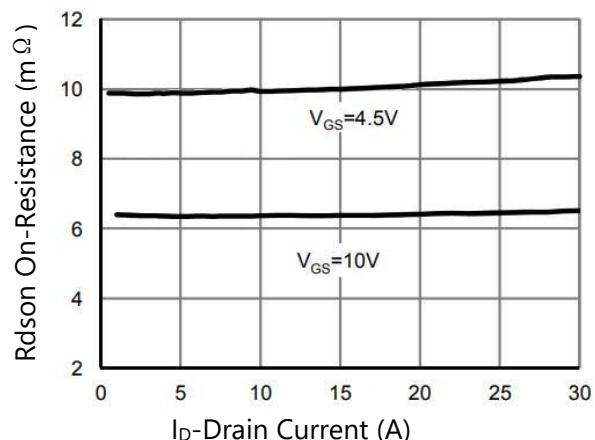
Drain-Source Diode Characteristics

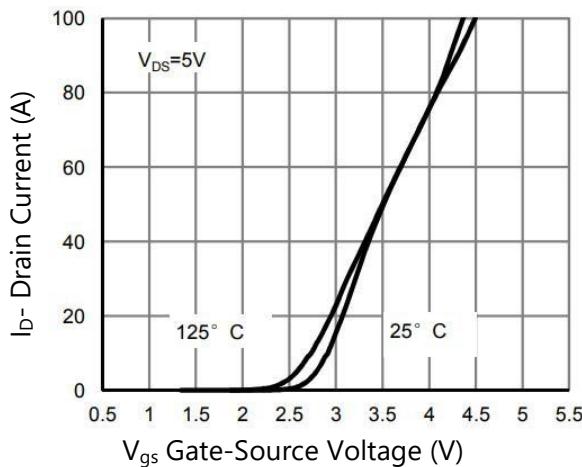
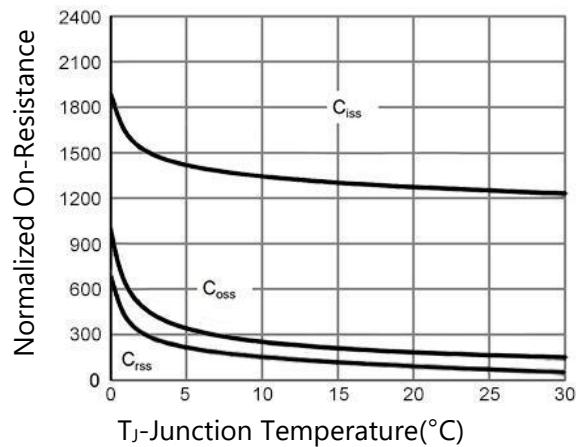
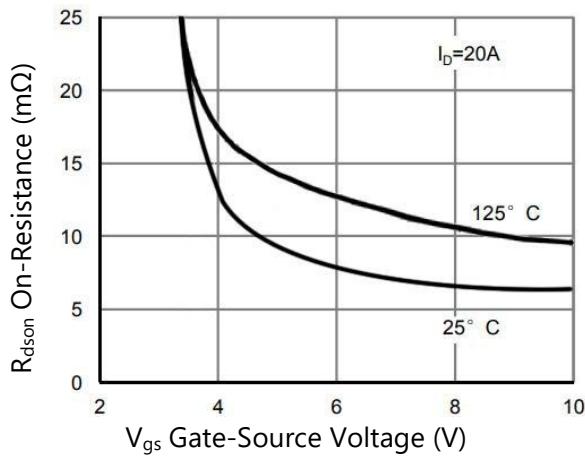
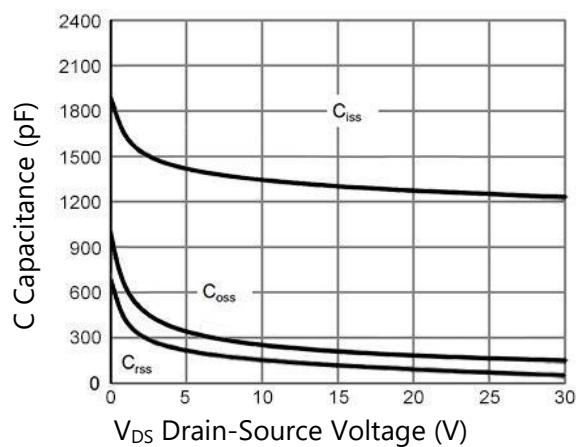
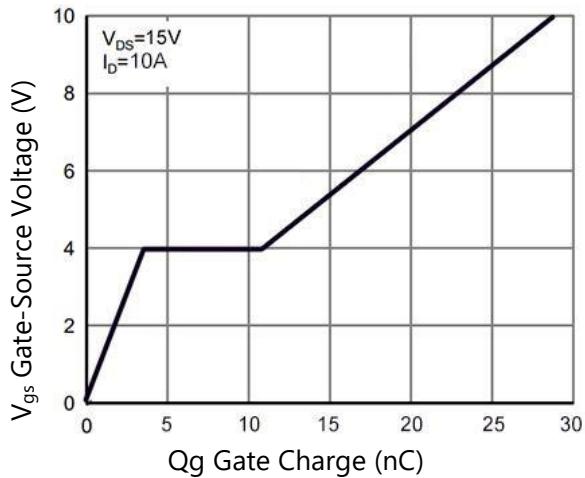
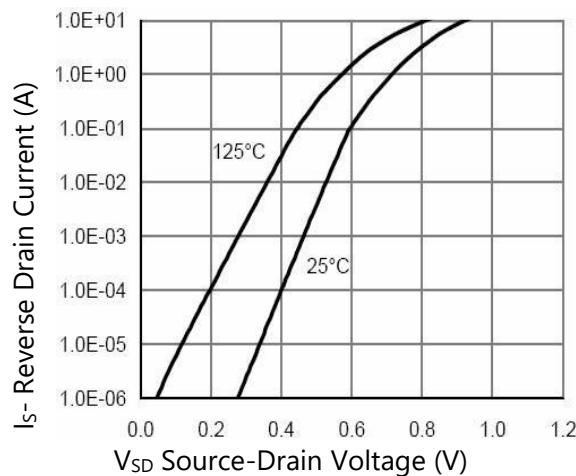
Diode Forward Voltage ^(Note 3)	V_{SD}	$V_{\text{GS}}=0\text{V}, I_{\text{s}}=-1\text{A}$	-	-	-1.2	V
Diode Forward Current ^(Note 2)	I_{s}		-	-	25	A

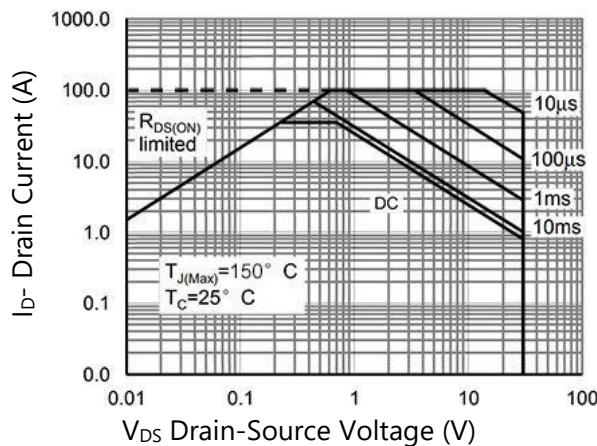
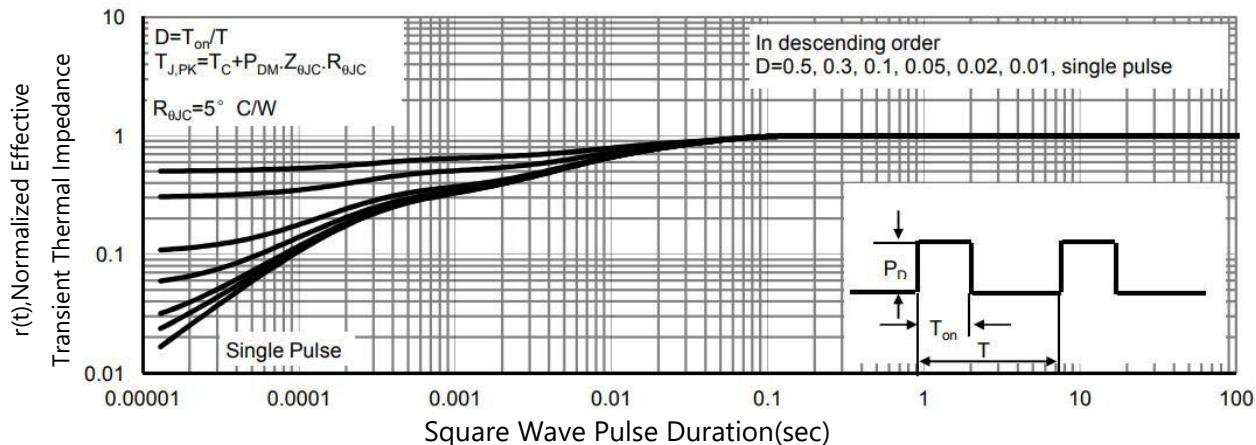
Note 2. Surface Mounted on FR4 Board, $t \leq 10$ sec.

Note 3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.

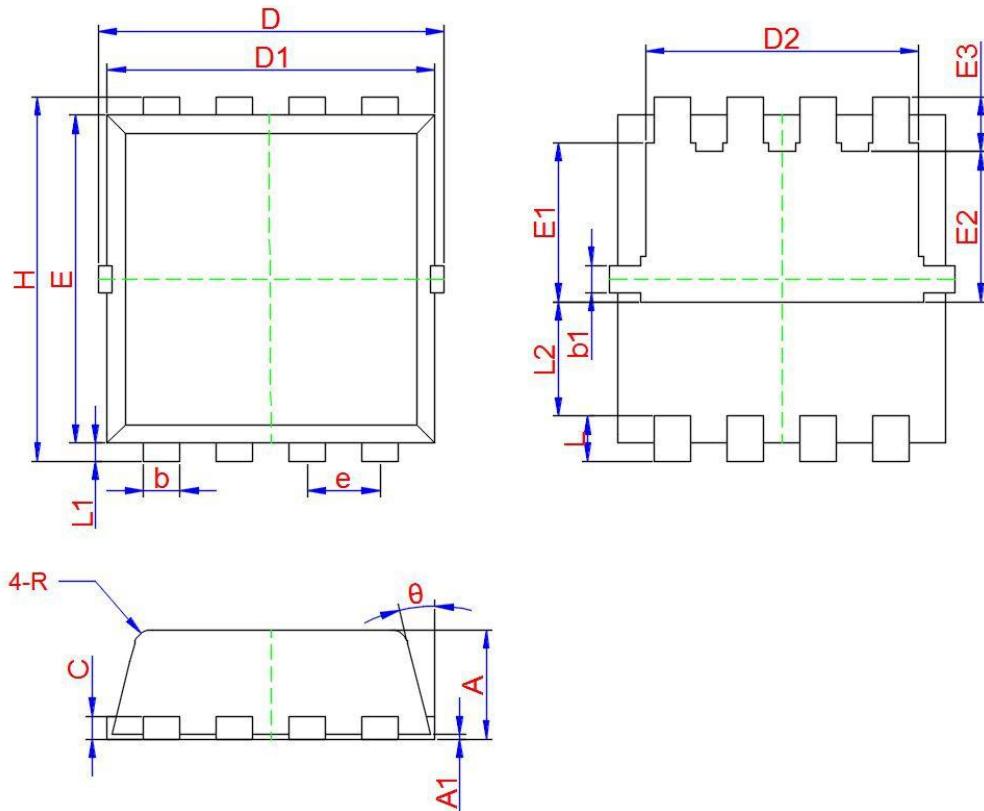
Note 4. Guaranteed by design, not subject to product.


TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS
Figure 1. Switching Test Circuit

Figure 2. Switching Waveform

Figure 3. Power De-rating

Figure 4. Drain Current

Figure 5. Output Characteristics

Figure 6. R_{dson} vs Drain Current



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS
Figure 7. Transfer Characteristics

Figure 8. $R_{ds(on)}$ vs Junction Temperature

Figure 9. $R_{ds(on)}$ vs V_{gs}

Figure 10. Capacitance vs V_{DS}

Figure 11. Gate Charge

Figure 12. Source- Drain Diode Forward



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS
Figure 13. Safe Operation Area

Figure 14. Normalized Maximum Transient Thermal Impedance


PACKAGE INFORMATION

DFN3X3-8L


Symbol	Dimensions In Millimeters			Symbol	Dimensions In Millimeters		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	0.700	0.800	0.900	e	0.650 TYP.		
A1	0.000	0.030	0.050	H	3.200	3.300	3.400
b	0.240	0.300	0.350	L	0.300	0.400	0.500
b1	0.080	0.130	0.180	L1	0.100	0.150	0.200
c	0.152 TYP.			L2	1.130 TYP.		
D	3.250	3.320	3.400	R	0.200 TYP.		
D1	3.050	3.150	3.250	θ	6°	10°	14°
D2	2.400	2.500	2.600				
E	3.000	3.100	3.200				
E1	1.350	1.450	1.550				
E2	1.200	1.300	1.400				
E3	0.400	0.500	0.600				